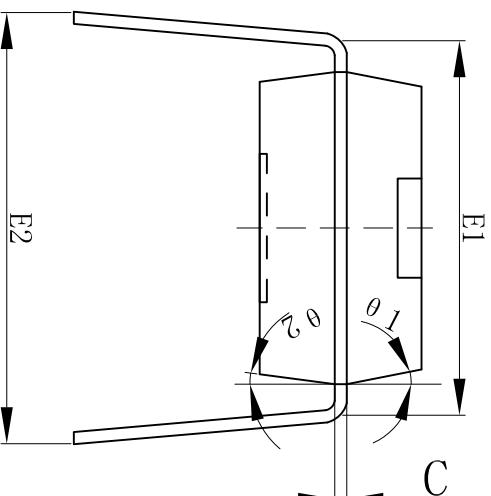
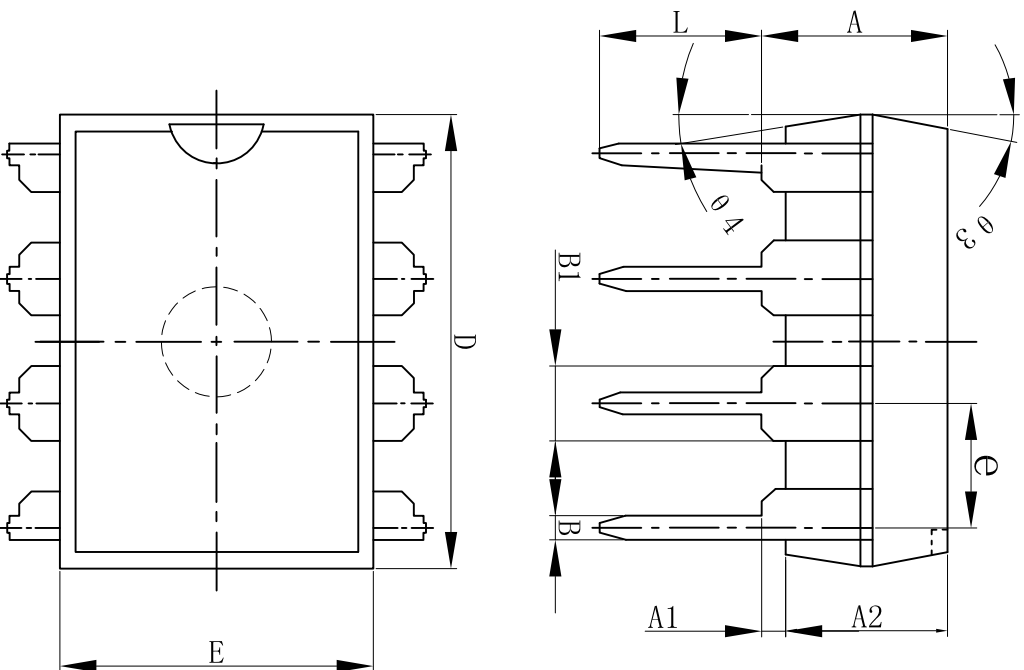




DIP8 PACKAGE OUTLINE DIMENSIONS



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	3.75	3.90	4.15
A1	0.60	—	—
A2	3.15	3.30	3.40
B	0.38	0.46	0.56
B1	1.52 (BSC)		
C	0.20	0.25	0.34
D	9.00	9.25	9.40
E	6.20	6.35	6.50
E1	7.35	7.62	7.85
e	2.54 (BSC)		
L	3.00	3.30	3.60
E2	8.00	8.40	8.80
theta 1	8°	~	16°
theta 2	8°	~	12°
theta 3	8°	~	14°
theta 4	6°	~	12°

技术说明:

1) LEADFRAME MATERIAL: COPPER;

引线框架材料: 铜;

2) LEADFRAME THICKNESS: 0.254mm;

引线框架厚度: 0.254mm;

3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;

塑封体长度及宽度尺寸不包括塑封溢胶;

4) REFERENCE: JEDEC MS-013, MS-012.

参考标准: JEDEC MS-013, MS-012.